LTx02 (fcBGA)

The fcBGA package is the main platform in flip Chip package family and a package subsystem meeting the standard BGA footprint that contains multiple components within the same package. Options also include configurations with thin core, Pb-free and Cu Pillar bump. This feature produces the lowest possible thermal resistance (Theta JC) between the package and any externally applied thermal solution.

1. Package Summary

Package Type Description	*fc*FBGA
Package Body Material Type	Plastic
Mounting Method Type	Surface Mount
Package Size	6.0 x 5.0mm
Ball Count	35
Solder Ball Materials	Pb free
Overall Package Thickness	1.28mm
Solder Ball Pitch	0.8mm

2. Application

SATCOM
Satellite Terminal Transmitter, Satellite Payload Transmitter
Telecommunications
Network products(LAN), Switching Transmission Cellular Base Stations

3. Feature

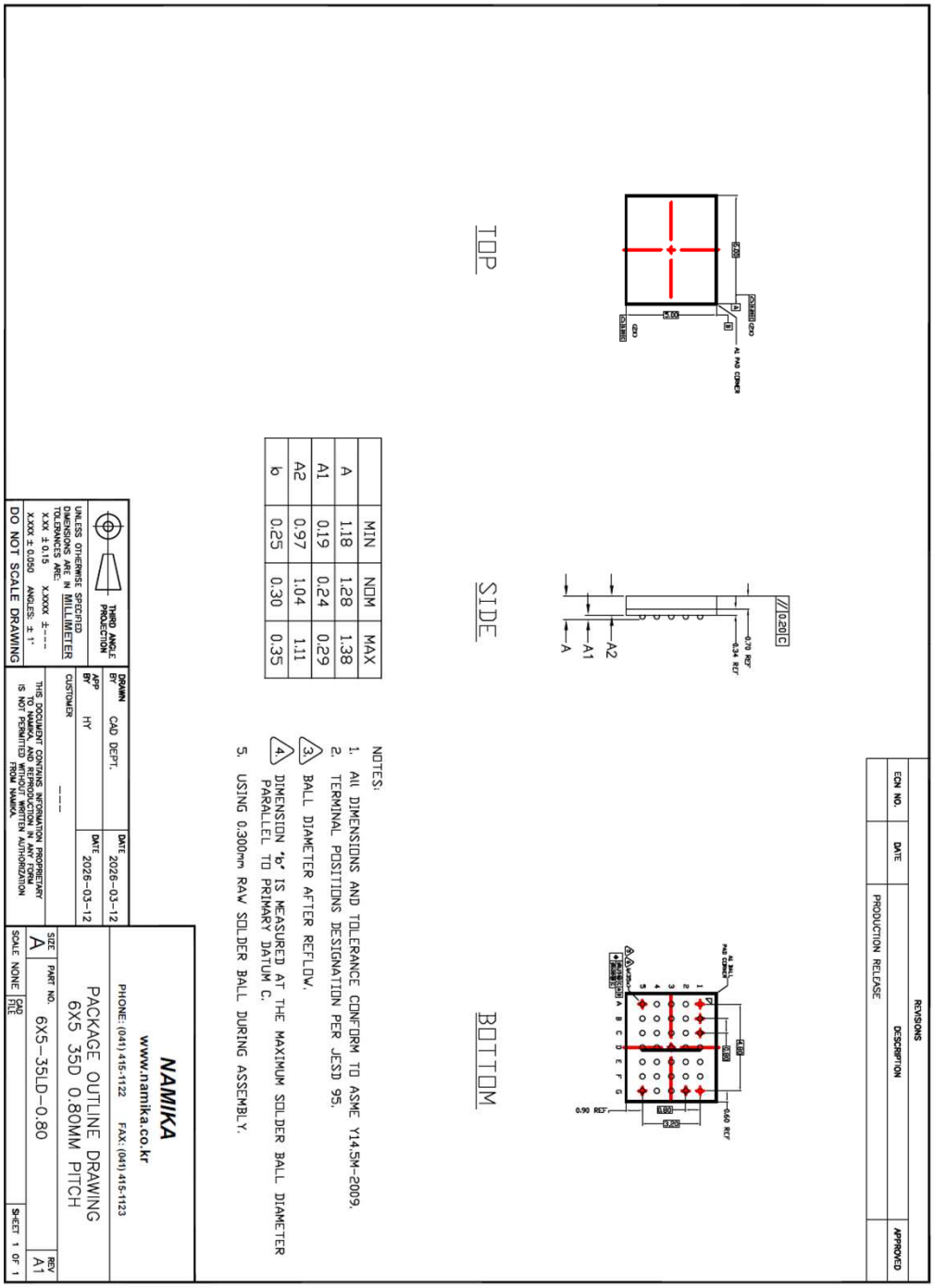
Substrate Layer	4
Product Type	fcBGA
Bump Count	126
Ball Count	35
Line & Space	20/30
Thickness	340um ± 40um
Die Size	4.07 x 2.47mm
Die Thickness	320um
Bump Pitch	260um
Bump Height	107um
Bump Size	130um
Package Size	6.0 x 5.0mm
PSR Opening	100um

NAMIKA

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4. Package Outline Dimension



NAMIKA